REMARKS

Claims 4 and 5 currently remain in the application. Claims 1-3 and 6-9 are canceled herein and claims 4 and 5 are herein amended.

Claims 1-3 were rejected under 35 U.S.C. 102 as being anticipated by JP11-114808. In part in view of the Examiner's reasons for rejection, claims 1-3 are herein canceled and hence the rejection is now a moot point.

Claim 4 was rejected under 35 U.S.C. 103 over JP11-114808 in view of Sinclair-Day. JP11-114808 discloses a polishing agent somewhat similar to that according to this invention but the polishing agent of JP11-114808 is produced by firstly obtaining compound particles by using a bowl to attach smaller particles on the surfaces mother particles and secondly by dispersing these compound particles in a dispersant ([0029] of JP11-114808). According to the method of claim 4 herein, by contrast, mother particles are added into a polishing liquid in which very fine abrading particles are dispersed and the mixture is stirred so as to obtain the subject polishing agent. In other words, JP11-114808 does not disclose or hint at the method of claim 4 herein.

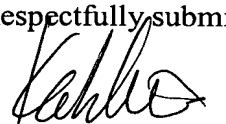
Sinclair-Day produces compound particles by using "top and bottom heating plates" (column 29, line 36) to obtain mixed press-molded particles (column 29, lines 45-52) and by grinding them (column 29, lines 53-59). In other words, the agglomerates of Sinclair-Day are individual particles that are bonded together such that the composite particles do not break down under the mechanical and/or electrostatic forces associated with application of the composition to the surface (Abstract lines 22-26), that is, they are very strongly bonded particles. According to the present invention, the mother particles merely carry the abrading particles, and they are not bonded so strongly as to be practically inseparable by ordinary mechanical or electrostatic forces. In particular, Sinclair-Day does not disclose or even hint at any production method including the step of adding mother particles into a liquid having fine abrading particles dispersed therein and the step of stirring them together. Thus, it should be concluded that the method according to claim 4 herein is not obvious even if JP11-114808 and Sinclair-Day are considered together in combination.

Claims 5-9 were rejected under 35 U.S.C. 103 over Towery in view of JP11-114808. In part in view of the Examiner's reasons for rejection, claim 5 has been amended to clearly say that a lapping plate is used for the polishing operation and the polishing liquid of this invention is directly supplied onto this lapping plate without using any polishing pad.

It should be noted that the polishing method according to JP11-114808 involves the step of using a polishing cloth comprising synthetic suede or foamed polyurethane and that the method according to Towery includes the use of a rotating polishing pad or block 16 or array of pads or blocks by a force FT (column 4, lines 39-42). In summary, both cited references are teaching the use of a lapping plate having a polishing pad or a polishing cloth attached while amended claim 5 herein is limited by the step of supplying a polishing liquid directly on the lapping plate, not onto a polishing pad or a polishing cloth. Such a polishing method wherein a polishing liquid is supplied directly onto the lapping plate is not disclosed or even hinted at by either of the cited references. It is therefore to be concluded that these cited references cannot predicate the rejection of amended claim 5 even if considered together in combination.

It is therefore believed that the instant Amendment is completely responsive to the Office Action and hence that the application is now in condition for allowance.

Respectfully submitted,



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